

09-13-2001

Form PTO-1595  
6-93  
OMB No. 0651-0011 (exp. 4/94)



101841777

U.S. Department of Commerce  
Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

## 1. Name of conveying party(ies):

Charles E. May

08/30/01

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

## 2. Name and address of receiving party(ies):

Name: LSI Logic CorporationStreet Address: 1551 McCarthy BoulevardCity: Milpitas, California ZIP 95035Country: United States of AmericaAdditional name(s) & address(es) attached? ☐ Yes ☒ No

## 3. Nature of Conveyance:

☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other \_\_\_\_\_

Execution Date(s): 08/29/01

## 4. Application number(s) or patent number(s):

09/19/3403

If this document is being filed together with a new application, the execution date of the application is 08/29/01

A. Patent Application No(s)

B. Patent No(s)

Additional numbers attached? ☐ Yes ☒ NoTitle of Invention: Semiconductor Wafer Arrangement and Method of Processing a SemiconductorLSI Logic Docket No. 01-145Our Docket No.: 1003-0602

## 5. Name and address of party to whom correspondence concerning documents should be mailed:

Name: Sandeep Jaggi

Internal Address: LSI Logic Corporation  
Intellectual Property Department  
Mail Stop D-106

Street Address: 1551 McCarthy Boulevard  
City: State: Zip: Milpitas, California 95035

## 6. Total number of applications and patents involved

1

7. Total fee (37 CFR §3.41): \$.40.00

☐ Enclosed  
☒ Authorized to be charged to deposit account

8. Deposit Account number: 12-2252

(Attach duplicate copy of this page if paying by deposit account)

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## 9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Bradford G. Addison

Name of Person Signing

Registration No. 41,486

Signature

August 30, 2001

Date

total number of pages including cover sheet, attachments and document 2

09/13/2001 DBYRNE

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40.00 CH

Mail documents to be recorded with required cover sheet information to:  
Commissioner of Patents and Trademarks, Box Assignments  
Washington, D.C. 20231

PATENT  
REEL: 012144 FRAME: 0952

Received: 8/29/01 7:36AM;

317 638 2139 -&gt; LSI LOGIC; Page 5

08/29/01 WED 09:33 FAX 317 638 2139

MAGINOT ADDISON &amp; MOORE

005

Docket No. 01-145

PATENT

**ASSIGNMENT**

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/WE, the undersigned, Charles E. May and Henanshn Bhatt, do hereby sell, assign, and transfer to: LSI LOGIC CORPORATION, a corporation of Delaware, having a place of business at 1551 McCarthy Boulevard, Milpitas, California 95035, ("Assignee"), its successors, assigns, and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all inventions and improvements which are disclosed in the application for United States Letters Patent,

- (X) which has been executed by the undersigned concurrently herewith.  
( ) which was filed on \_\_\_\_\_ and assigned Serial No. \_\_\_\_\_.

and is entitled: "Semiconductor Wafer Arrangement and Method of Processing a Semiconductor Wafer" and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application; and

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications to patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Name: Charles E. May Date: 8-28-01, 2001 Witness: Donna Hooper  
Printed Name

Name: Henanshn Bhatt Date: \_\_\_\_\_, 2001 Witness: \_\_\_\_\_  
Printed Name

Assignment

**ASSIGNMENT**

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/WE, the undersigned, Charles E. May and Hemanshu Bhatt, do hereby sell, assign, and transfer to: LSI LOGIC CORPORATION, a corporation of Delaware, having a place of business at 1551 McCarthy Boulevard, Milpitas, California 95035, ("Assignee"), its successors, assigns, and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all inventions and improvements which are disclosed in the application for United States Letters Patent,

- ( X ) which has been executed by the undersigned concurrently herewith,  
 ( ) which was filed on \_\_\_\_\_ and assigned Serial No. \_\_\_\_\_.

and is entitled: "Semiconductor Wafer Arrangement and Method of Processing a Semiconductor Wafer" and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application; and

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications to patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Name: \_\_\_\_\_ Date: \_\_\_\_\_, 2001 Witness: \_\_\_\_\_  
 Charles E. May

Witness: \_\_\_\_\_  
 Printed Name

Name: \_\_\_\_\_ Date: \_\_\_\_\_, 2001 Witness: \_\_\_\_\_  
 Hemanshu Bhatt

Witness: \_\_\_\_\_  
 Printed Name

Assignment